WHAT IS CLAIMED IS:

1. A processing method for forming a chip with a side surface in which a stair-shaped cutout part is formed by executing full cutting by a second blade with a thinner blade thickness than a first blade after executing, by the first blade, half cutting for a package substrate in which multiple planned dividing lines that intersect are set, the processing method comprising:

a half cutting step of causing the first blade to cut into the package substrate and cutting the package substrate by the first blade along the planned dividing line to form a first cut groove and form an uncut residual part under the first cut groove;

a full cutting step of cutting the uncut residual part along the first cut groove by the second blade thinner than the first blade after the half cutting step is executed; and

a tip shape check step of checking a tip shape of the first blade, the tip shape check step comprising

estimating a tip shape of the first blade on a basis of an image obtained through imaging; and

calculating a cutting-in depth of the first blade with which a depth of the cutout part becomes a predetermined depth on a basis of the tip shape of

the first blade estimated by the estimating section and the blade thickness of the second blade,

wherein,

in the half cutting step, the first blade is caused to cut into the package substrate to the cutting-in depth that is calculated on the basis of the tip shape of the first blade checked in the tip shape check step and the blade thickness of the second blade.

2. The processing method according to claim 1, wherein,

in the tip shape check step, a cut mark is formed in an upper surface of the package substrate by the first blade, and the tip shape of the first blade is checked on a basis of the cut mark.

3. The processing method according to claim 2, wherein,

in the tip shape check step, the cut mark is formed in the outer circumferential surplus region of the upper surface of the package surface by the first blade.

4. The processing method according to any one of claims 1 to 3, further comprising:

a planarization step of correcting and planarizing a tip of the first blade at a predetermined timing.

5. The processing method according to claim 4,

wherein,

a present timing is determined as the predetermined timing by determining whether or not the cutting-in depth calculated in the tip shape check step is equal to or larger than the value according to a thickness of an electrode disposed at a center of the planned dividing line.

6. A cutting apparatus that forms a chip with a side surface in which a stair-shaped cutout part is formed by executing full cutting by a second blade with a thinner blade thickness than a first blade after executing, by the first blade, half cutting for a package substrate in which multiple planned dividing lines that intersect are set , the cutting apparatus comprising:

a table that holds the package substrate;

a first cutting unit having the first blade that cuts the package substrate along the planned dividing line to form a first cut groove and form an uncut residual part under the first cut groove;

a second cutting unit having the second blade that cuts the uncut residual part along the first cut groove and is thinner than the first blade;

an imaging unit that images a cut mark formed through causing the first blade to cut into a cutting

target object; and

a control unit that controls the respective constituent elements, wherein

the control unit includes

an estimating section that estimates a tip shape of the first blade on a basis of an image obtained through imaging by the imaging unit, and

a calculating section that calculates a cutting-in depth of the first blade with which a depth of the cutout part becomes a predetermined depth on a basis of the tip shape of the first blade estimated by the estimating section and the blade thickness of the second blade.

7. The cutting apparatus according to claim 6, wherein,

when the cutting-in depth calculated by the calculating section is determined to be equal to or larger than a value according to the thickness of an electrode disposed at a center of the planned dividing line, a processing control section of the control unit determines that a present timing is a predetermined timing when flat dressing is executed for the tip of the cutting edge of the first blade.